

trustEd and fleXible system-on-Chip

gives the floor to...



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WHAT IS YOUR BACKGROUND?

Bachelor Degree in SW Engineering and Automation. SW Manager responsible for **Avionic SW** Communication, equipment until 2008, SW Manager responsible of Basic and Platform SW for **ELECTRONICS BU of Selex ES** (a Finmeccanica company) until 2012, Engineering Capability Manager of Electronic Equipment & Communication LoB Engineering of BU ELECTRONICS in **Leonardo S.p.A** to date

WHAT IS THE ROLE OF YOUR ORGANIZATION IN THE PROJECT? WHAT IS YOUR ROLE?



What are the expected ACHIEVEMENTS FOR YOUR WP?

WP3 Requirements Work Package aims at collecting the user (OEMs) needs order to provide an agreed requirements baseline for SoC and SiP, and the roadmap identification towards a European supply chain for secure high performance digital SoC/SiP. We will:

- Perform Selection of use cases (reference products/applications) to identify requirements
- SoC/SiP requirements identification
- Validation Plan of the subset of requirements to be demonstrated in the scope of EXCEED project
- Definition of evaluation board requirements and specifications for a demonstrator
- Gaps analysis between full set of identified requirements and a subset demonstrated
- Roadmap of the European Supply Chain to fill the Gaps for European Defence industry applications

My roles are: WP3 Leader and acting as Leonardo representative in the governance bodies

We expect to:

• Exploit syn

- Exploit synergies and drive technology evolution to better fit the AS&D industry needs.
- Identify Gaps and Roadmap to resolve/mitigate Dependence on non-EU sources for SoC/SiP technology to support all identified reference products/applications.

A European source, such as that envisaged by the EXCEED project, could cover the needs for a significant percentage of OEM future products, especially in security-sensitive developments, provided that performance and costs are competitive with the current State of the Art.

OEM: Original Equipment Manufacturer | SoC: System-on-Chip | SiP: System-in-package



WHAT WILL EXCEED BRING TO YOU AND YOUR ORGANISATION?

The EXCEED project enables to contribute in shaping the future of the European semiconductor industry in order to **better fit the needs of the AS&D sector**, building the foundation for a stronger, more competitive, secure European defence.

It also gives the opportunity to pursue synergies among different product families, to foresee a wider market for the European semiconductor industry and to strengthen its position in the field of security-critical applications.

In the end we have the privilege joining a team of experts and building a network of technology excellence across the European Union.



